

**IN THE CLAIMS**

The listing of claims will replace all prior versions, and listings, of claims in the application:

1. (*Currently Amended*) A method of positioning an object at a required position on ~~an~~ a first object table in a lithographic projection apparatus, comprising:
  - placing an object at a first position on a the first object table;
  - measuring a displacement between the first position of the object and a required position of the object on the first object table;
  - removing the object from the first object table;
  - translating the removed object, the first object table, or both, relatively relative to each other by substantially the said measured displacement, in a direction substantially parallel to the plane of the first object table; and
  - placing the object at substantially the required position on the first object table.
2. (*Previously Amended*) A method according to claim 1, wherein said measuring comprises aligning a first mark on the object to a second mark.
3. (*Previously Presented*) A method according to claim 2, wherein said second mark is located on the one of the first object table and a second object table.
4. (*Previously Presented*) A method according to claim 1 wherein a mask is held by the first object table.
5. (*Previously Presented*) A method according to claim 2, wherein said second mark is located on one of a mask and a substrate.
6. (*Previously Presented*) A method according to claim 1, wherein said measuring is accomplished using imaging means to determine the displacement between the first position of the object and the required position of the object.

7. (*Previously Presented*) A method according to claim 1, wherein said measuring comprises processing information about the first position of the object, together with information regarding the required position of the object to determine said displacement.

8. (*Cancelled*).

9. (*Original*) A method according to claim 1, wherein said object is held in place using a vacuum generating surface.

10. (*Cancelled*).

11. (*Currently Amended*) A method of positioning a substrate at a required position on a substrate table, said method comprising:

placing the substrate at a first position on the substrate table;

measuring a displacement between the first position of the substrate and a required position of the substrate on the substrate table;

removing the substrate from the substrate table;

translating the substrate, the substrate table, or both, relatively relative to each other by substantially the said displacement, in a direction substantially parallel to the plane of the substrate table; and

placing the substrate at substantially the required position on the substrate table.

12. (*Withdrawn*) A device manufacturing method comprising:

(a) providing a substrate table with a substrate which is at least partially covered by a layer of radiation-sensitive material;

(b) patterning a projection beam to produce a pattern in its cross-section; and

(c) projecting the patterned beam onto a target portion of the layer of radiation-sensitive material:

prior to said projecting, placing the substrate at a first position on the substrate table;

measuring a displacement between the first position of the substrate and a required position of the substrate;

removing the substrate from the substrate table;

moving the substrate and the substrate table relatively to each other by substantially the said displacement, in a direction substantially parallel to the plane of the second object table; and

placing the substrate at substantially the required position on the second object table.

13. (*Withdrawn*) A device manufactured in accordance with a method according to claim 12.

14. (*Previously Presented*) A method according to claim 1, wherein a first surface of the object contacts the first object table, and wherein the required position corresponds to a position of the object at which a clamping force that clamps the object on the first object table is substantially homogenous on the first surface of the object.

15. (*Previously Presented*) A method according to claim 1, wherein the translating includes translating the object, the first object table, or both, relatively to each other in two directions.

16. (*Previously Presented*) A method according to claim 11, wherein said measuring comprises aligning a first mark on the substrate to a second mark.

17. (*Previously Presented*) A method according to claim 11, wherein said measuring is accomplished using an imaging device to determine the displacement between the first position of the substrate and the required position of the substrate.

18. (*Previously Presented*) A method according to claim 11, wherein said measuring comprises processing information about the first position of the substrate, together with information regarding the required position of the substrate to determine said displacement.

19. (*Previously Presented*) A method according to claim 11, wherein a first surface of the substrate contacts the substrate table, and wherein the required position corresponds to a position of the substrate at which a clamping force that clamps the substrate on the substrate table is substantially homogenous on the first surface of the substrate.

20. (*Previously Presented*) A method according to claim 11, wherein the translating includes translating the substrate, the substrate table, or both, relatively to each other in two directions.